Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP MSR3044 Router(JG405A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing		0

radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#
tweezers	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew the screws for mounting angle 1, and then remove the mounting angle 1 from the rack or cabinet.
2. Unscrew the screws on mounting angle 2, and then remove the mounting angle 2.
3. Remove all of the labels.
4. Unscrew the screws on filler panel 3 and 4, and then remove the filler panel 3 and 4.
5. Remove shielding fingers 5.
6. Remove the part 6 and 7. Unscrew the screws on top cover 8, and then remove the top cover 8.
7. Remove shielding fingers 5.
8. Unscrew the screws on part 9, 10 and 11, and then remove them.
9. Unscrew the screws on part 12, and then remove it.
10. Unscrew the screws on part 9.1, and then remove PCB 9.2.
11. Unscrew the screws on fan 11.1, and then remove part 11.2.
12. Unscrew the screws on part 12.1, and then remove PCB 12.2.
13. Unscrew the screws on part 13.1, and then remove PCB 13.2.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations)

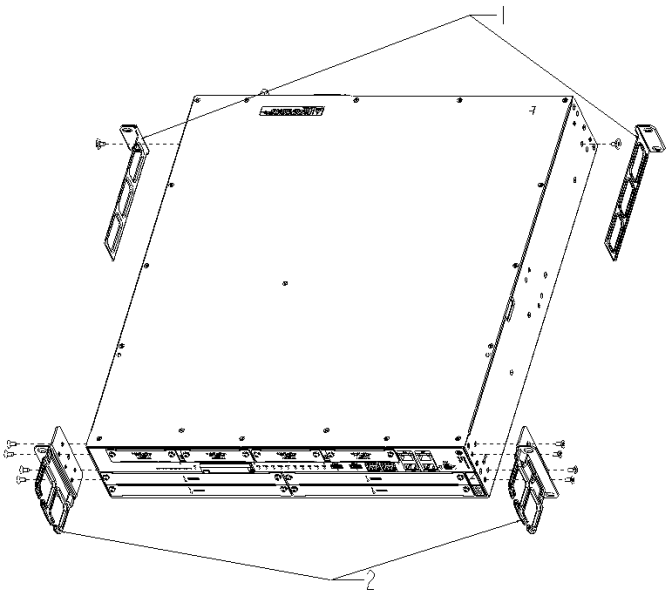

Figure 1 Remove mounting angle

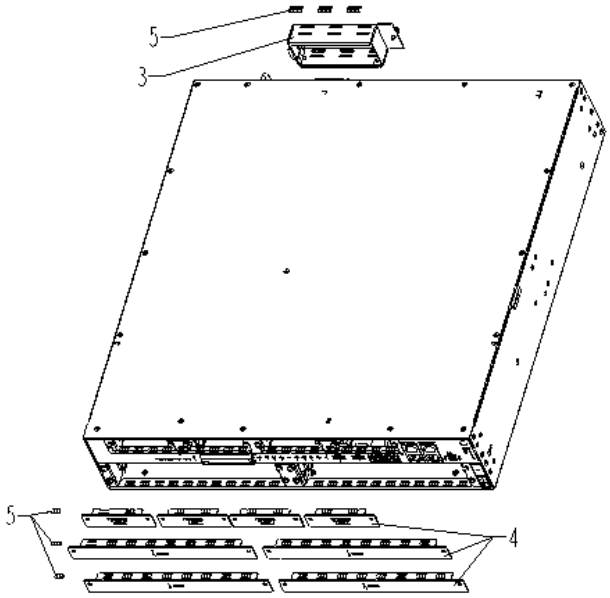

Figure 2 Treatments to the blank panel

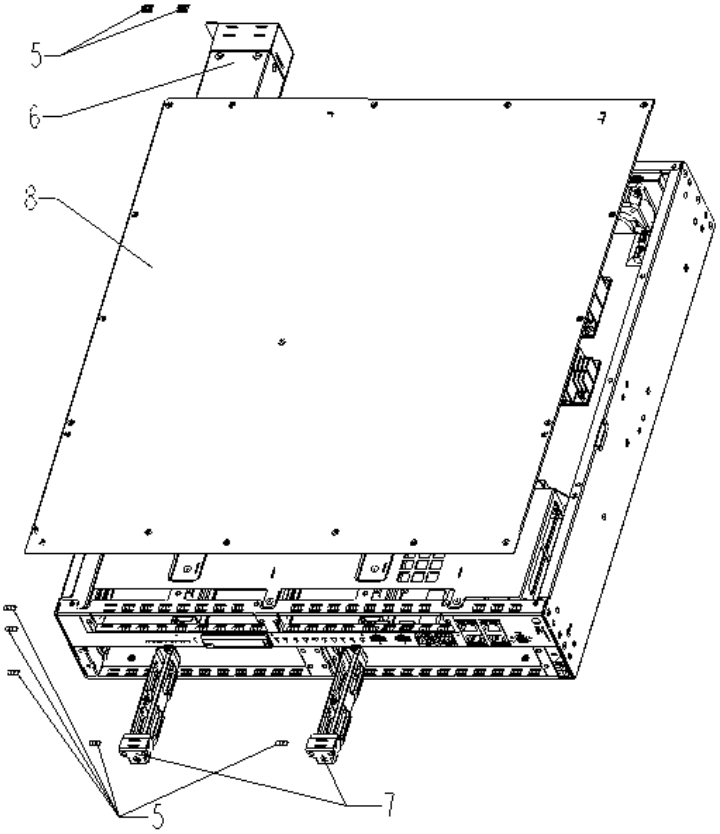

Figure 3 Treatments to the product

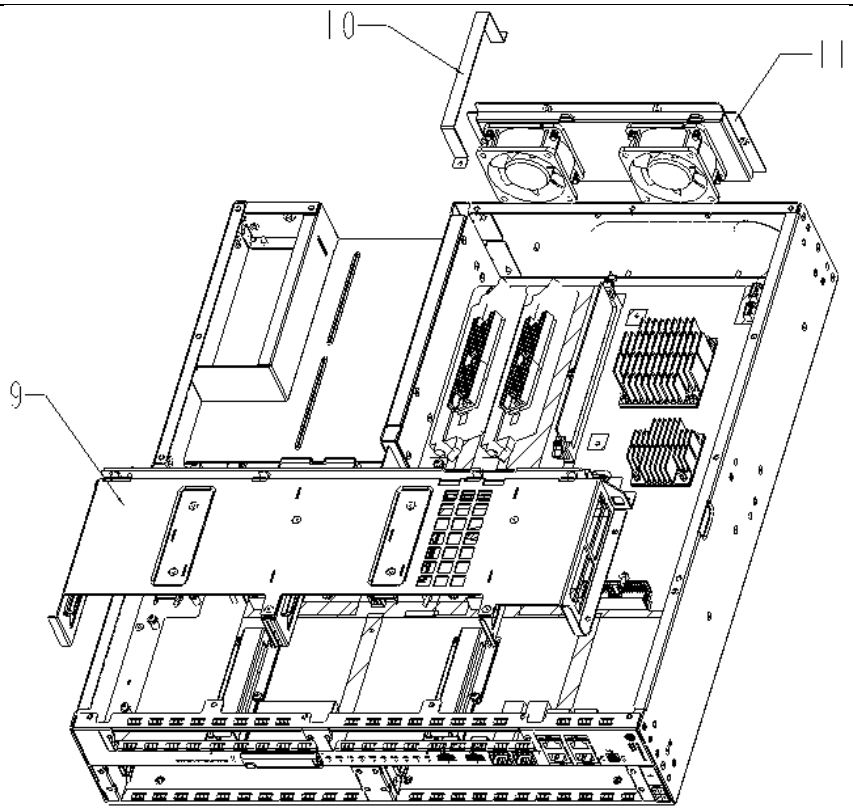

Figure 4 Treatments to the product

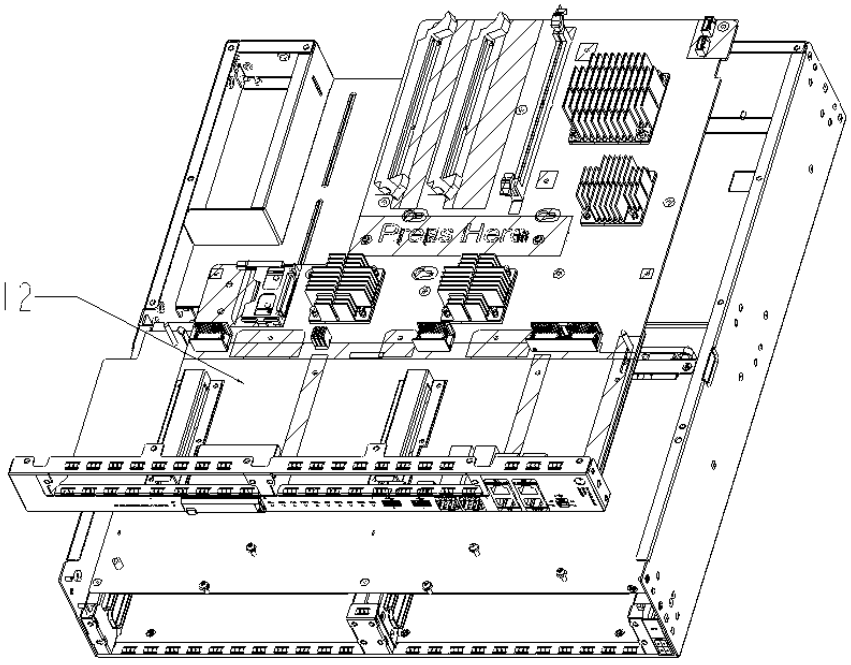

Figure 5 Treatments to the product

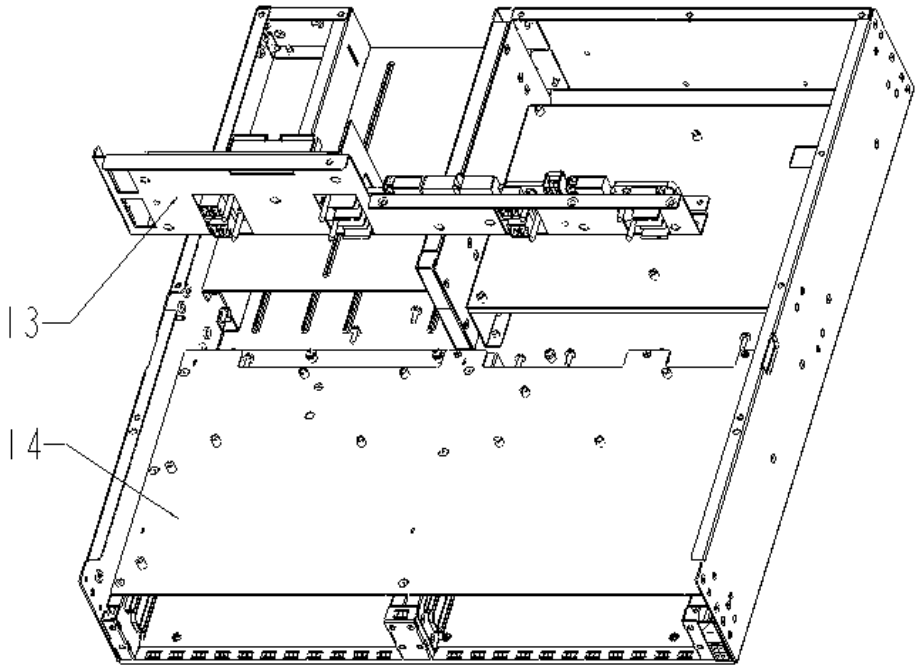

Figure 6 Treatments to the product

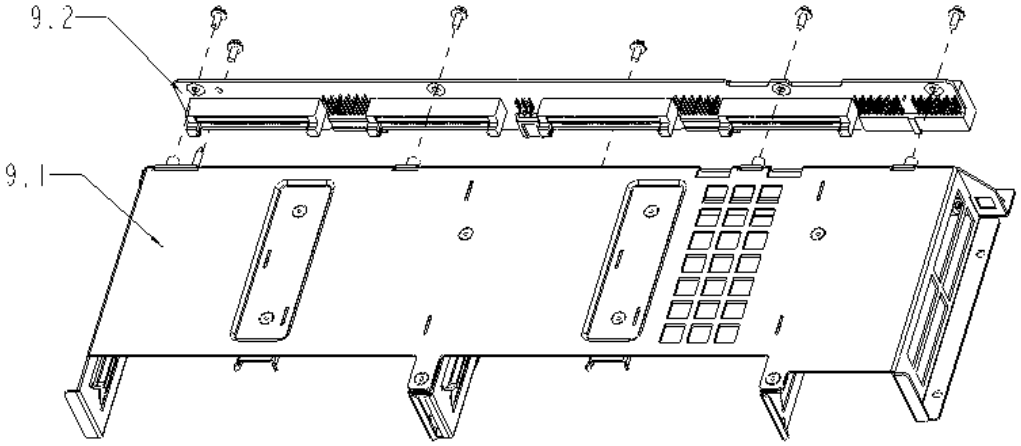

Figure 7 Treatments to PCB-assembly

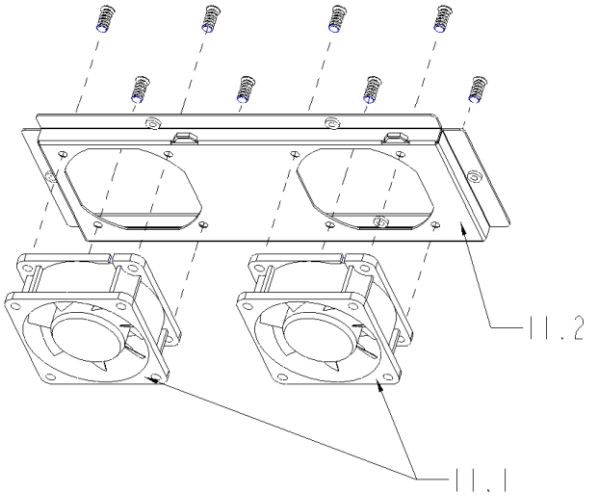

Figure 8 Treatments to the fan-assembly

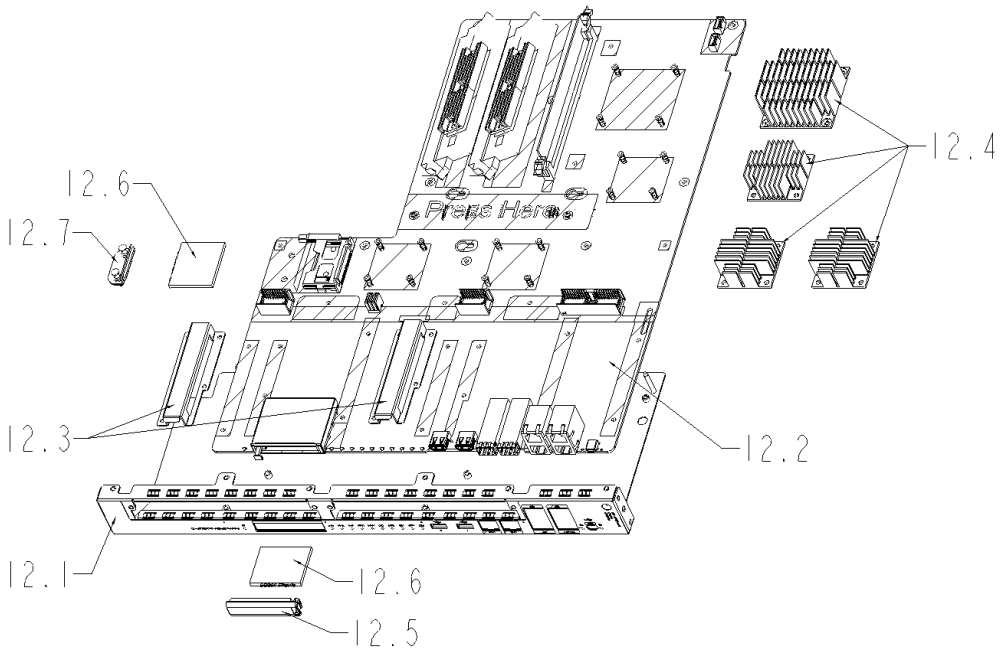

Figure 9 Treatments to PCB-assembly

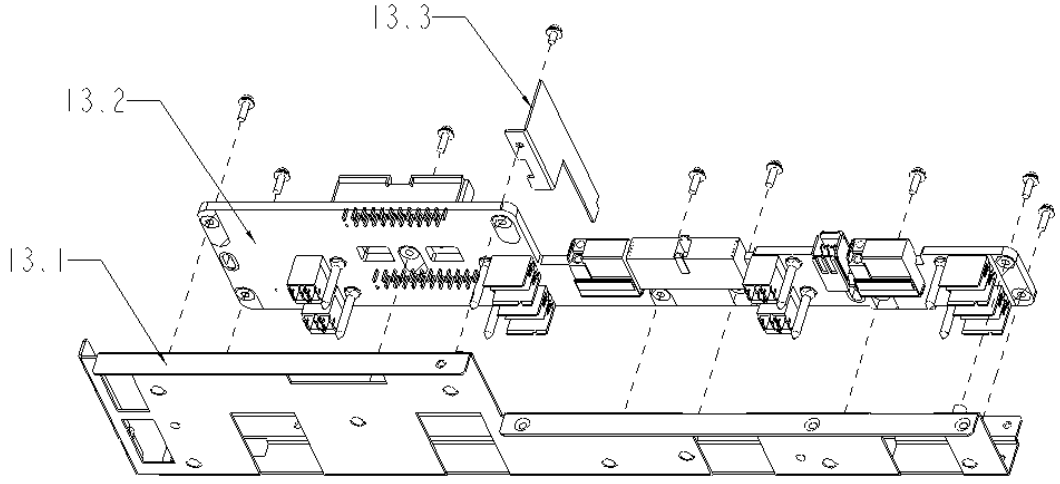

Figure 10 Treatments to PCB-assembly

3.3 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Clear the yellow adhesive, if had, by the tweezers.
2. Pry the button battery up from socket.

3.4 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations)

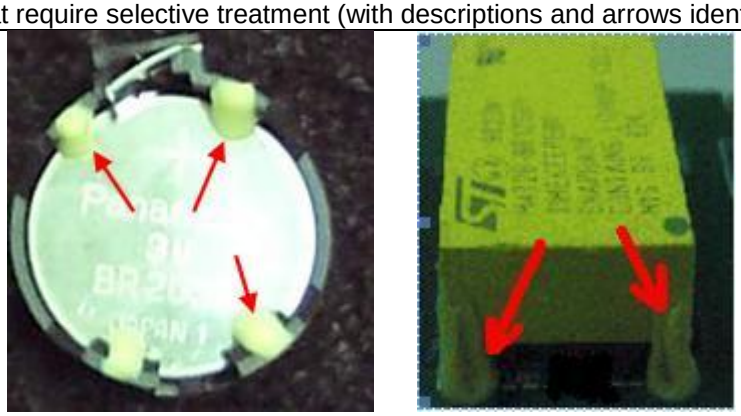

Figure 11 Clear the yellow adhesives by the tweezers.

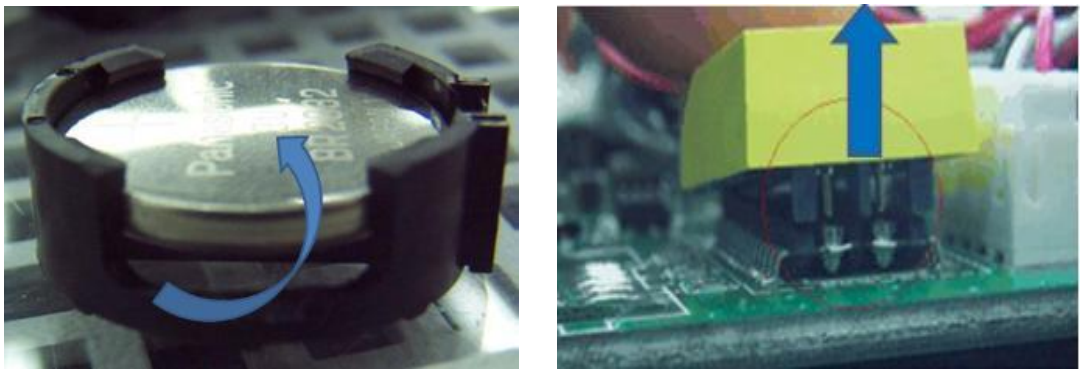

Figure 12 Pry up the button battery

3.5 Material of the facility built

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details
1		Fe	84	0.63%		Fe recycling
2		Fe	150	1.13%		Fe recycling
3		Fe	96	0.73%		Fe recycling
4		Fe	308	2.33%		Fe recycling
5		Be-Cu	6	0.05%		Cu recycling
6		Fe	341	2.58%		Fe recycling
7		Fe	108	0.82%		Fe recycling
8		Fe	1790	13.52%		Fe recycling
9	9.1	Fe	746	5.64%		Fe recycling
	9.2	Complex PCB	100	0.76%	The surface of PCB is greater than 10 square centimeters;	
10		Fe	15	0.11%		Fe recycling
11	11.1	PC	109*2	1.65%	Containing brominated flame retardants	Fan
	11.2	Fe	125	0.94%		Fe recycling
12	12.1	Fe	674	5.09%		Fe recycling
	12.2	Complex PCB	837	6.32%	The surface of PCB is greater than 10 square centimeters;	
	12.3	Fe	60	0.45%		Fe recycling
	12.4	AL	163	1.23%		AL recycling
13	13.1	Fe	343	2.59%		Fe recycling
	13.2	Complex PCB	300	2.27%	The surface of PCB is greater than 10 square centimeters;	
	13.3	Fe	15	0.11%		Fe recycling
14		Fe	6975	52.70%		Fe recycling

4.0 Revised record

Date	Version	Author	Modify content
2012.12.26	V0	Wu Xuejun	Initial version